## **EAST Search History**

## **EAST Search History (Prior Art)**

Ref#	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L32	6	30 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/05/21 15:46
L31	19	29 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/05/21 15:46
L30	442	(seed buffer intermediate under) near1 (layer film membrane) with (substrate wafer ceramic base semiconductor) with (between center middle interpos\$3) with (pattern\$4 hole opening) with (charge or static or ESD or electric or surge or shock or electrostatic or discharge or radiation or noise or conductive)	US-PGPUB; USPAT	OR	ON	2010/05/21 15:45
L29	2239	(seed buffer intermediate under) near1 (layer film membrane) with (substrate wafer ceramic base semiconductor) with (touch \$3 contact\$3) with (pattern \$4 hole opening)	US-PGPUB; USPAT	OR	ON	2010/05/21 15:44
L28	34	26 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/05/21 15:41
L27	173	25 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/05/21 15:41
L26	2266	(seed buffer intermediate under) near1 (layer film membrane) with (substrate wafer ceramic base semiconductor) with (between center middle interpos\$3) with (pattern\$4 hole opening)	US-PGPUB; USPAT	OR	ON	2010/05/21 15:41
L25	7274	(seed buffer intermediate under) near1 (layer film membrane) with (substrate wafer ceramic base semiconductor) with (between center middle interpos\$3) with (copper Cu chromium Cr Si silicon Ta metal\$4)	US-PGPUB; USPAT	OR	ON	2010/05/21 15:41

L22	4	20 and "428"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/05/21 14:54
L21	2	20 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/05/21 14:54
L20	74	17 and 18	US-PGPUB; USPAT	OR	ON	2010/05/21 14:54
L19	14	17 same 18	US-PGPUB; USPAT	OR	ON	2010/05/21 14:31
L18	27468	(seed buffer intermediate under) near2 (layer film membrane) with (substrate wafer ceramic base semiconductor) with (top over above)	US-PGPUB; USPAT	OR	ON	2010/05/21 14:31
L17	1268	(between middle center intermediate) near2 (film layer membrane) with (position\$3 align\$4 identif\$6 data information) near1 (mark pattern tag label number)	US-PGPUB; USPAT	OR	ON	2010/05/21 14:30
L16	2	15 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/05/21 14:30
L15	131	(seed buffer intermediate under) with (substrate wafer ceramic base semiconductor) with (film layer membrane) with (top over above) with (position\$3 align\$4 identif\$6 data information) near1 (mark pattern tag label number)	US-PGPUB; USPAT	OR	ON	2010/05/21 14:29
L14	72	12 and "428"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/05/21 14:27
L13	22	12 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/05/21 14:17
L12	1460	(seed buffer intermediate under substrate) with (film layer membrane) with (top over above) with (position\$3 align\$4 identif\$6 data information) near1 (mark pattern tag label number)	US-PGPUB; USPAT	OR	ON	2010/05/21 14:11
L11	19	("4377028"   "4414749"   "4936930").PN. OR ("5405810").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/05/21 14:10

L10	19	("4338620"   "4418467"   "4479830"   "4893163"   "5002902"   "5106432"   "5270255"   "5300797"   "5316966"   "5369050"   "5405810"   "5462636"   "5525840"   "5786267"   "5847468"   "5861320"   "5939132").PN. OR ("6534159").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/05/21 13:18
L9	2	("6534159"   "6886239").PN. OR ("7057260").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/05/21 13:10
L8	3	("2003/0182789").URPN.	USPAT	OR	ON	2010/05/21 13:10
L7	0	("2006/0187588").URPN.	USPAT	OR	ON	2010/05/21 13:06
L5	20	4 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/05/21 13:01
L4	1328	(position\$3 align\$4 identif\$6 data information) near1 (mark pattern tag label number) with (seed buffer intermediate under over substrate) with (film layer wafer) with (between center middle)	US-PGPUB; USPAT	OR	ON	2010/05/21 13:01
S35	0	S32 and 360/137.ccls.	US-PGPUB; USPAT	OR	ON	2010/05/21 11:47
S34	0	S32 and 360/235.3.ccls.	US-PGPUB; USPAT	OR	ON	2010/05/21 11:46
S33	110	S32 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/05/21 11:46
S32	448	S28 and S29 and S30	US-PGPUB; USPAT	OR	ON	2010/05/21 11:43
S31	13	S28 same S29 same S30	US-PGPUB; USPAT	OR	ON	2010/05/21 11:36
S30	176986	(slider head magnetic) with (MR sensor transducer)	US-PGPUB; USPAT	OR	ON	2010/05/21 11:36
\$29	321943	(seed buffer intermediate under over substrate) with (metal\$4) with (layer film membrane portion etch\$4 pattern section mark)	US-PGPUB; USPAT	OR	ON	2010/05/21 11:35

S28	35253	(position\$3 align\$4 identif\$6 data information) with (mark pattern tag label number) with (seed buffer intermediate under over substrate) with (film layer wafer)	US-PGPUB; USPAT	OR	ON	2010/05/21 11:34
S27	120	S26 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/04/27 17:09
S26	5445	(position\$3 align\$4 identif\$6 data information) near2 (mark pattern tag label number) with (seed buffer intermediate under over substrate) near2 (film layer)	US-PGPUB; USPAT	OR	ON	2010/04/27 17:08
S25	12	("4166574"   "5294812"   "5516430"   "5721651"   "5764454"   "5837963"   "5984190"   "6202289"   "6313436"   "6344892"   "6449123").PN. OR ("7114239").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/04/27 17:07
S24	2	S23 and S12	US-PGPUB; USPAT	OR	ON	2010/04/27 17:06
S23	34962	(position\$3 align\$4 identif\$6 data information) with (mark pattern tag label number) with (seed buffer intermediate under over substrate) with (film layer wafer)	US-PGPUB; USPAT	OR	ON	2010/04/27 16:56
S22	23	S17 and (hitachi).as.	US-PGPUB; USPAT	OR	ON	2010/04/27 16:55
S21	0	S17 and S12	US-PGPUB; USPAT	OR	ON	2010/04/27 16:55
S20	120	S19 and @pd<="20050513"	US-PGPUB; USPAT	OR	ON	2010/04/27 16:39
S19	209	S17 and "430"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/04/27 16:39
S18	35	S17 and "360"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2010/04/27 16:21
S17	2349	(position\$3 align\$4 identif\$6 data information) near1 (mark pattern tag label number) with (seed buffer intermediate under over substrate) near1 (film layer water)	US-PGPUB; USPAT	OR	ON	2010/04/27 16:18

S16	103	(position\$3 align\$4 identif\$6 data information) near2 (mark pattern tag label number) and S15	US-PGPUB; USPAT	OR	ON	2010/04/27 16:09
S15	627	360/317.ccls.	US-PGPUB; USPAT	OR	ON	2010/04/27 16:09
S14	3	("2003/0036025").URPN.	USPAT	OR	ON	2010/04/27 15:32
S13	10	("20010048145"   "20020031732"   "20030036025"   "5175774"   "5302491"   "5837963"   "6312876"   "6449123"   "6731373").PN. OR ("6897010").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/04/27 15:24
S12	131	(neomax).as.	US-PGPUB; USPAT; USOCR	OR	ON	2010/04/27 14:57
S11	6	("5764454"   "5901021"   "5914285").PN. OR ("6277506").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/04/27 14:55
S10	22	("20010010612"   "20050264912"   "3799796"   "4454014"   "4681813"   "4713284"   "4796127"   "4814915"   "4849290"   "4902651"   "5165981"   "5595946"   "5595947"   "5609948"   "5645898"   "5657192"   "5734534"   "5936813"   "6034847"   "6198607"   "6277506").PN. OR ("7675708").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2010/04/27 14:14
S9	55	360/235.3.ccls.	US-PGPUB; USPAT	OR	ON	2010/04/27 14:06
S8	126	360/235.1.ccls.	US-PGPUB; USPAT	OR	ON	2010/04/27 14:06
S7	80	360/125.39.ccls.	US-PGPUB; USPAT	OR	ON	2010/04/27 14:06
S6	47	360/125.38.ccls.	US-PGPUB; USPAT	OR	ON	2010/04/27 14:06
S5	55	360/125.41.ccls.	US-PGPUB; USPAT	OR	ON	2010/04/27 14:05
S4	20	360/123.45.ccls.	US-PGPUB; USPAT	OR	ON	2010/04/27 14:05
S3	23	360/123.24.ccls.	US-PGPUB; USPAT	OR	ON	2010/04/27 14:05

82	14	("20020008946"   "20020126423"   "20040066575"   "20050024772"   "20050174687"   "4796127"   "4814915"   "5894388"   "5729411"   "5901021"   "6048632"   "6078479"   "6277506"   "6870706").PN.	US-PGPUB; USPAT	OR	ON	2010/04/27 13:55
S1	1	10/559704.app.	US-PGPUB; USPAT	OR	ON	2010/04/27 13:55

## 5/21/2010 3:51:25 PM

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